# Power MOSFET, N-Channel, SUPERFET<sup>®</sup> III, Easy Drive, 650 V, 65 A, 40 m $\Omega$

### Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET Easy drive series helps manage EMI issues and allows for easier design implementation.

### Features

- 700 V @ T<sub>J</sub> = 150°C
- Typ.  $R_{DS(on)} = 35.4 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 136 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 1154 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

### Applications

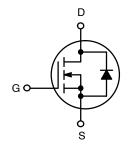
- Telecom / Server Power Supplies
- Industrial Power Supplies
- UPS / Solar



# **ON Semiconductor®**

### www.onsemi.com

V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
650 V	40 mΩ @ 10 V	65 A

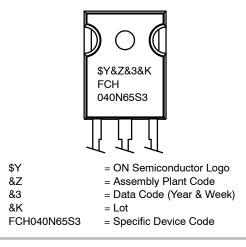


**POWER MOSFET** 



TO-247 LONG LEADS CASE 340CH

### MARKING DIAGRAM



### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter		FCH040N65S3-F155	Unit
V <sub>DSS</sub>	Drain to Source Voltage		650	V
V <sub>GSS</sub>	Gate to Source Voltage	– DC	±30	V
		– AC (f > 1 Hz)	±30	
I <sub>D</sub>	Drain Current	– Continuous (T <sub>C</sub> = 25°C)	65	А
		– Continuous (T <sub>C</sub> = 100°C)	41	
I <sub>DM</sub>	Drain Current	– Pulsed (Note 1)	162.5	А
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		358	mJ
I <sub>AS</sub>	Avalanche Current (Note 2)		8.1	А
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		4.17	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	very dv/dt (Note 3) 20		
PD	Power Dissipation	(T <sub>C</sub> = 25°C)	417	W
		– Derate Above 25°C	3.33	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8"	from Case for 5 seconds	300	°C

### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse width limited by maximum junction temperature. 2.  $I_{AS} = 8.1 \text{ A}, R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}C$ . 3.  $I_{SD} \leq 32.5 \text{ A}, \text{ di/dt} \leq 200 \text{ A/}\mu\text{s}, V_{DD} \leq 400 \text{ V}, \text{ starting } T_J = 25^{\circ}C$ .

### **THERMAL CHARACTERISTICS**

Symbol	Parameter	FCH040N65S3-F155	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH040N65S3-F155	FCH040N65S3	TO-247 G03	Tube	N/A	N/A	30 Units

### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	
OFF CHARACT	FF CHARACTERISTICS						
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 1 \text{ mA}, \text{ T}_{J} = 25^{\circ}\text{C}$	650	-	-	V	
		$V_{GS}$ = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C	700	-	-	V	
$\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 1$ mA, Referenced to $25^{\circ}C$	-	0.64	_	V/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ = 650 V, $V_{GS}$ = 0 V	-	-	1	μΑ	
		$V_{DS} = 520 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	4.5	-		
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS}$ = ±30 V, $V_{DS}$ = 0 V	-	-	±100	nA	
N CHARACTE	RISTICS						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 6.5 \text{ mA}$	2.5	-	4.5	V	
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 32.5 A	-	35.4	40	mΩ	
<b>9</b> FS	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 32.5 A	-	46	-	S	

### **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted) (continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
YNAMIC CHA	ARACTERISTICS	· · ·				
C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 400 V, $V_{GS}$ = 0 V, f = 1 MHz	-	4740	-	pF
C <sub>oss</sub>	Output Capacitance	1	-	120	_	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	1154	_	pF
Coss(er.)	Energy Related Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	171	_	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 32.5 A, V <sub>GS</sub> = 10 V (Note 4)	-	136	-	nC
Q <sub>gs</sub>	Gate to Source Gate Charge		-	33	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		-	59	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.7	-	Ω
VITCHING C	HARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 32.5 \text{ A},$	-	35	-	ns
t <sub>r</sub>	Turn-On Rise Time	V <sub>GS</sub> = 10 V, R <sub>g</sub> = 3.3 Ω (Note 4)	-	51	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	95	-	ns
t <sub>f</sub>	Turn-Off Fall Time			30	-	ns
URCE-DRA	IN DIODE CHARACTERISTICS	•		-	-	
۱ <sub>S</sub>	Maximum Continuous Drain to Source	Diode Forward Current	-	-	65	А
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diod	e Forward Current	_	_	162.5	А

5						
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	_	162.5	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{SD} = 32.5 \text{ A}$	-	_	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V, I_{SD} = 32.5 A,$	-	534	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/µs	-	13.6	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

# **TYPICAL PERFORMANCE CHARACTERISTICS**

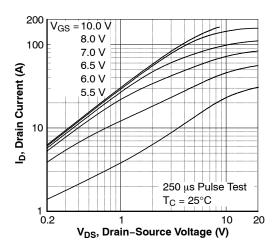


Figure 1. On-Region Characteristics

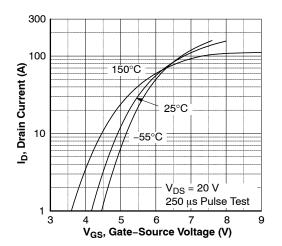
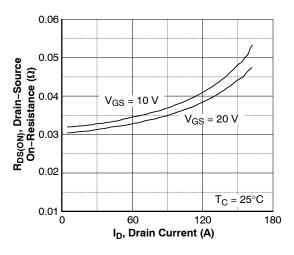
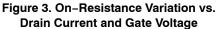


Figure 2. Transfer Characteristics

### TYPICAL PERFORMANCE CHARACTERISTICS (continued)





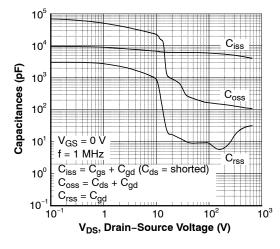
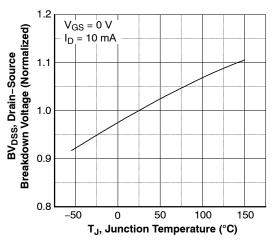


Figure 5. Capacitance Characteristics





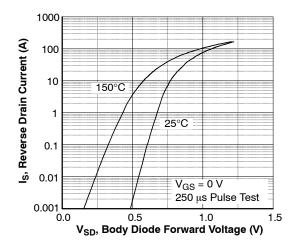


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

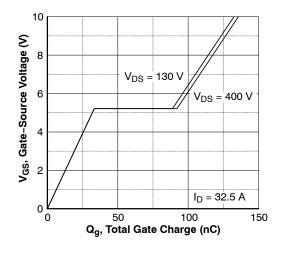
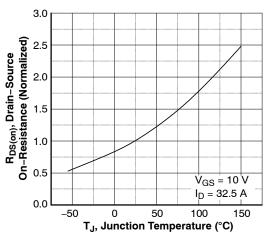


Figure 6. Gate Charge Characteristics





## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

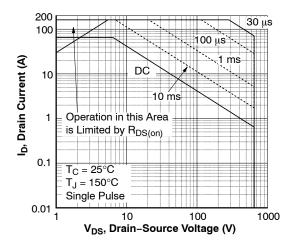


Figure 9. Maximum Safe Operating Area

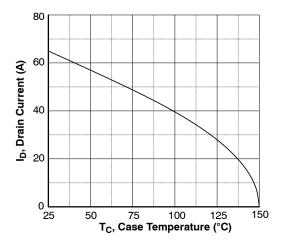


Figure 10. Maximum Drain Current vs. Case Temperature

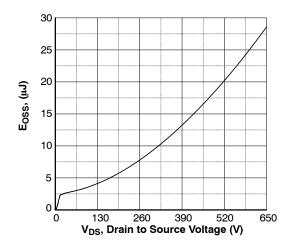


Figure 11. E<sub>OSS</sub> vs. Drain to Source Voltage

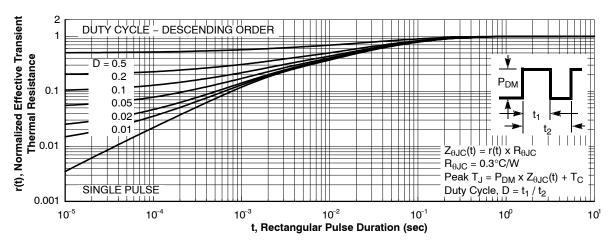
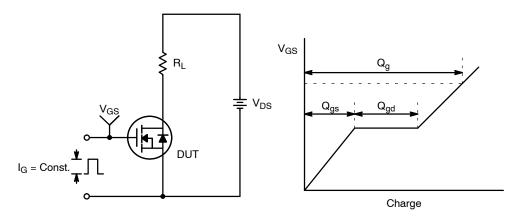


Figure 12. Transient Thermal Response Curve





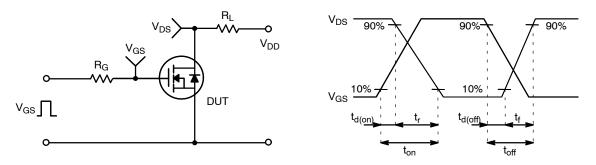
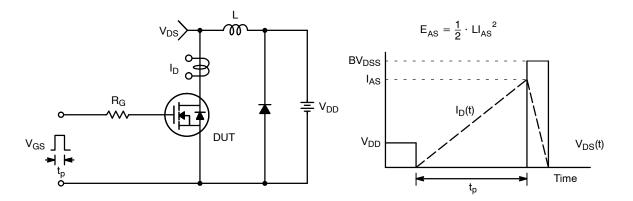


Figure 14. Resistive Switching Test Circuit & Waveforms





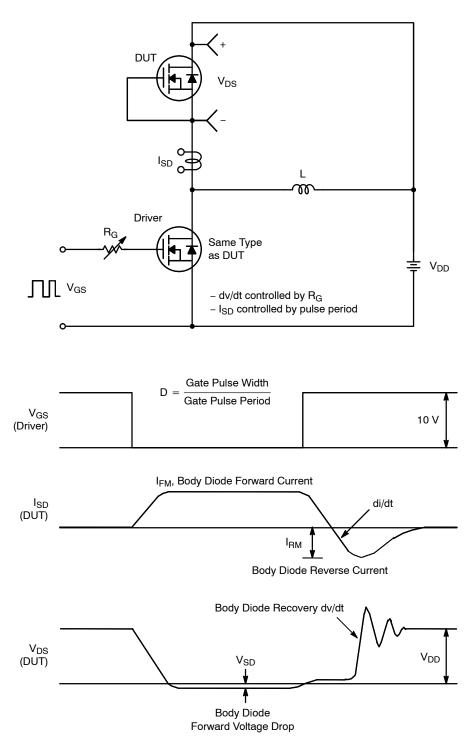


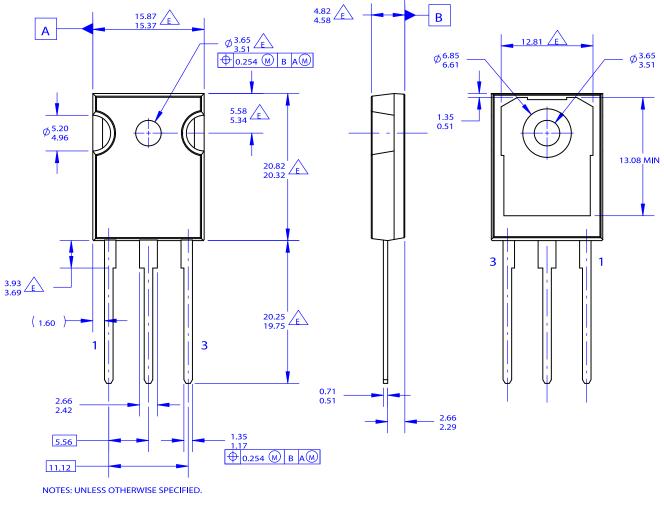
Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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